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DESCRIPTION

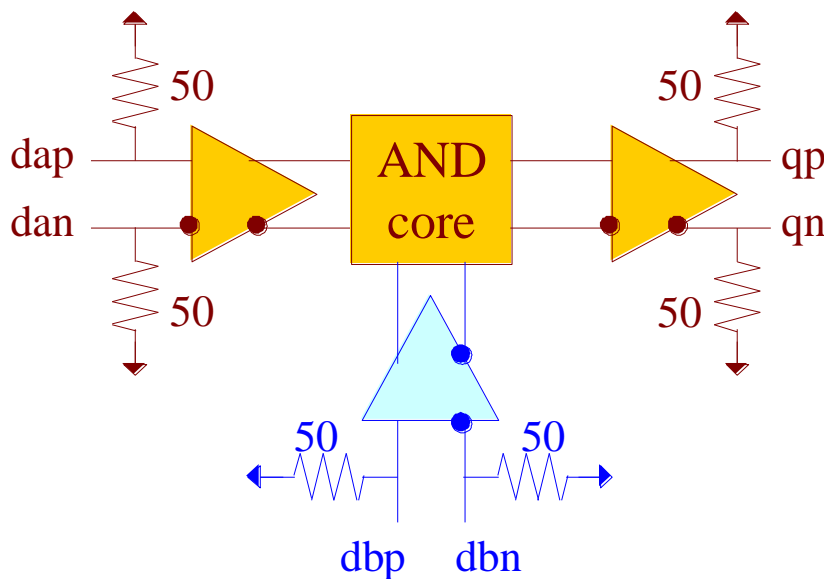


Fig. 1. Functional Block Diagram

This SiGe IC provides broadband AND/OR Boolean logic functionality, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can AND/OR a high-speed data input signal **dap/dan** with another high-speed data input signal **dbp/dbn**, and deliver a high-speed NRZ data output signal **qp/qn**. An RZ data output signal can be generated by inserting up to half of the IC's maximum data input frequency into one data input signal **dap/dan** or **dbp/dbn** while providing an up to its maximum clock signal analog bandwidth into the other data input **dap/dan** or **dbp/dbn**.

The part's I/O's support the CML logic interface with on chip 50 *Ohms* termination to **vcc** and may be used differentially, AC/DC coupled, single-ended, or in any combination (also see POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either negative supply (**vcc** = 0.0 V = ground and **vee** = -3.3 V), or positive supply (**vcc** = +3.3 V and **vee** = 0.0 V = ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50 *Ohms* termination to ground. Different PCB layouts will be needed for each different power supply combination.

All the characteristics detailed below assume **vcc = 0.0V and **vee** = -3.3V.**



ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings shown in Table 1 may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Ratings.

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.35	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°C
Storage Temperature	-40	+100	°C
Operational Humidity	10	98	%
Storage Humidity	10	98	%

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
High-Speed I/Os			
dap	21	CML input	Differential data/clock inputs with internal SE 50 <i>Ohms</i> termination to vcc .
dan	23		
dbp	3	CML input	Differential data/clock inputs with internal SE 50 <i>Ohms</i> termination to vcc .
dbn	5		
qp	11	CML output	Differential data outputs with internal SE 50 <i>Ohms</i> termination to vcc . Require external SE 50 <i>Ohms</i> termination to vcc .
qn	9		
Supply and Termination Voltages			
Name	Description		Pin Number
vcc	Positive power supply. (+3.3V or 0)		2, 4, 6, 8, 10, 12, 14-18, 20, 22, 24
vee	Negative power supply. (0V or -3.3V)		1, 7, 13, 19



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
General Parameters					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
I _{vee}		95		mA	
Power consumption		315		mW	
Junction temperature	-40	25	125	°C	
HS Input Data/Clock (dap/dan) (dbp/dbn)					
Data Rate	DC		64	Gbps	When used to generate NRZ data
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
HS Output Data (qp/qn)					
Data Rate	DC		64	Gbps	
Logic “1” level		vcc		V	
Logic “0” level		vcc-0.4		V	With external 50 Ohms DC termination
Latency	36		50	ps	
Rise/Fall times			8	ps	20%-80%
Output Jitter		0.3		ps	Peak-to-peak

PACKAGE INFORMATION

The chip die is housed in a custom 24-pin CQFN package shown in Fig. 2. The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section to be soldered to the vcc plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5760-KHC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with Commission Delegated Directive (EU) 2015/863 of 4 June 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances (Text with EEA relevance) on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive) in accordance with the definitions set forth in the directives for all ten substances.

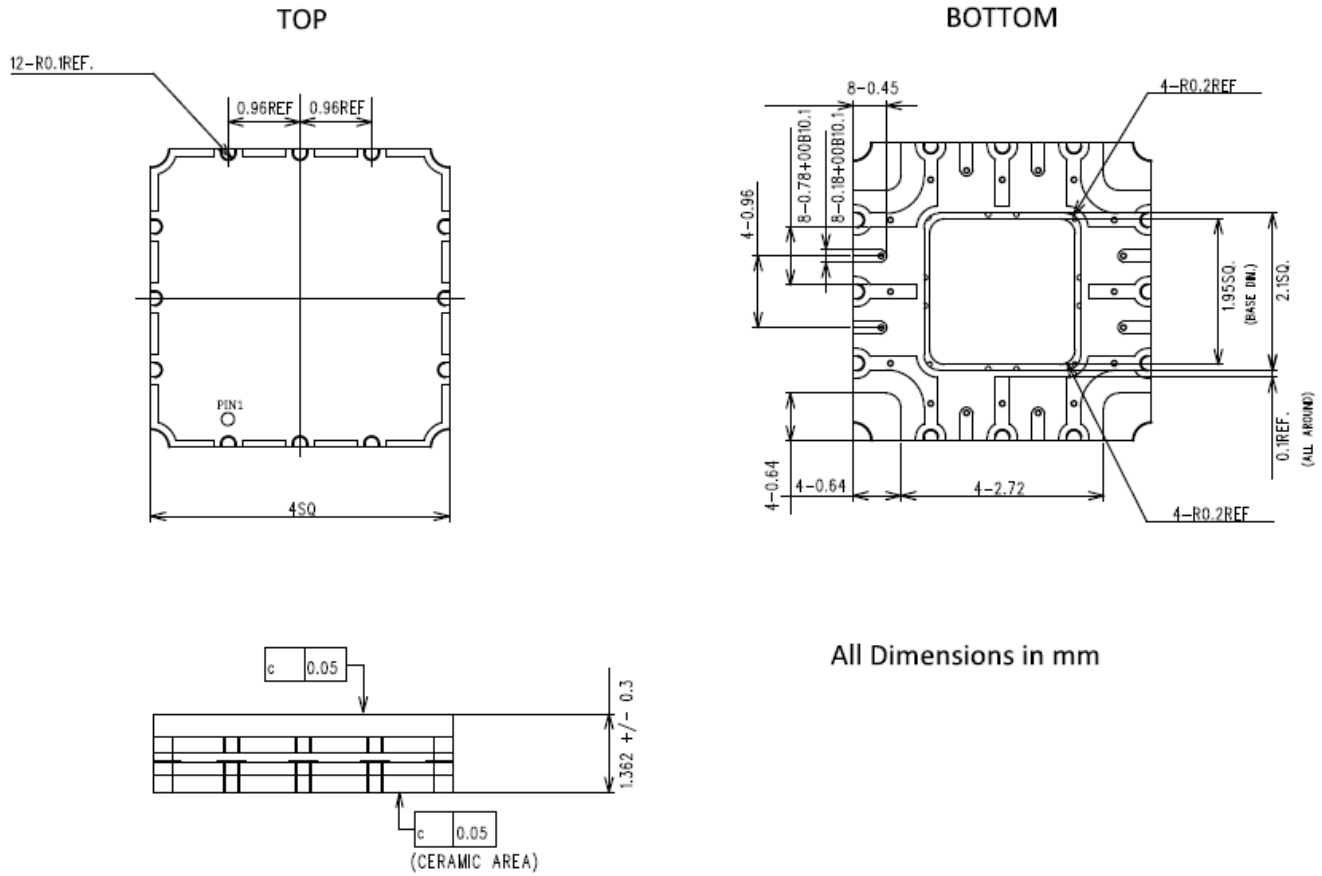


Fig. 2. CQFN 24-Pin Package Drawing (All Dimensions in mm)

REVISION HISTORY

Revision	Date	Changes
1.0.2	04-2025	Corrected latency information
0.0.2	02-2023	First release